

Docket No.: JCLA8288-D
Date: January 28, 2004

COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

ATTENTION: APPLICATION BRANCH

Sir:

This is a request for filing a continuation application under 37 CFR 1.53 (b) as a **divisional application** of prior application No. **10/144,121** filed on **May 10, 2002**.

Prior application information: **Examiner: LEE, EUGENE ; Group Art Unit: 2815**

The entire disclosure of the prior application, from which an oath or declaration is supplied herewith as indicated below, is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated by reference.

Transmitted herewith for filing is the patent application of

Inventor(s): **CHI-HSING HSU ;**
WEN-YUAN CHANG ;

For: SEMICONDUCTOR PACKAGING SUBSTRATE AND METHOD OF PRODUCING THE SAME

Enclosed are:

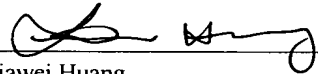
- (X) Specification in FIFTEEN (15) pages.
- (X) FIVE (5) sheets of drawings.
- (X) Preliminary Amendment.
- (X) A copy of Declaration and Power of Attorney from the prior application is enclosed.
- (X) Return prepaid postcard.

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$ 770	\$ 770
Total Claims	8 - 20 =	0 x	\$ 18	\$ 0
Independent Claims	1 - 3 =	0 x	\$ 86	\$ 0
If application contains any multiple dependent claims(s), then add			\$ 290	\$ 0
For a Large Entity:	TOTAL FILING FEE			\$ 770

- (X) A check in the amount of \$ 770 to cover the filing fee is enclosed.
- (X) The commissioner is authorized to charge any additional necessary fee to Account No. 50-0710 (Order No. JCLA8288-D). A duplicate copy of this sheet is enclosed.

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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

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Inventor(s) : CHI-HSING HSU ;
WEN-YUAN CHANG ;

For : SEMICONDUCTOR PACKAGING SUBSTRATE AND METHOD
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"Express Mail"
Mailing Label No. : EV 300987539 US

Date of Deposit : January 28, 2004

I hereby certify that the accompanying

Transmittal in Duplicate; Specification in 15 page(s); 5 sheets of
drawing(s); Copy of Declaration and Power of Attorney from prior
application; Preliminary Amendment; Checks for Filing Fee(s); Return
Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to
Addressee" service under 37 CFR 1.10 on the date indicated above and are
addressed to the Commissioner for Patents, P.O. BOX 1450, Alexandria, VA 22313-
1450


Michelle Chang